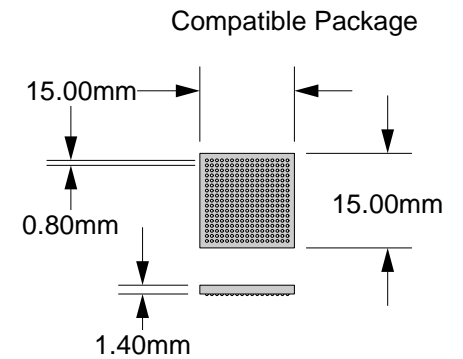



- 1 Substrate: 2.39mm \pm 0.18mm [0.094" \pm 0.007"]
FR4/G10 or equivalent high temp material.
17 μ m [1/2 oz.] Cu clad. SnPb plating.
- 2 Pins: shell material- Brass Alloy 360 1/2 hard;
finish- 0.25 μ m [10 μ] Au over 1.27 μ m [50 μ]
Ni (min.). Contact material- BeCu; finish
0.25 μ m [10 μ] Au over 2.54 μ m [100 μ] Ni
(min.).
- 3 Test points: material- Phosphor Bronze; plating-
Sn over 1.27 μ m [50 μ] Ni. Gold flash on contact
end.



Description: BGA Probe Board
217 position BGA GHz socket to 217 position female bottom interface.

 © 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	PB-BGA217B-Z-01 Drawing		Status: Released	Scale: 1:1.2	Rev: A
	Drawing: J. Glab		Date: 07/06/07		
	File: PB-BGA217B-Z-01 Dwg		Modified:		

Tolerances: diameters \pm 0.03mm [\pm 0.001"],
PCB perimeters \pm 0.13mm [\pm 0.005"],
PCB thicknesses \pm 0.18mm [\pm 0.007"],
pitches (from true position) \pm 0.08mm [\pm 0.003"],
all other tolerances \pm 0.13mm [\pm 0.005"]
unless stated otherwise. Materials and
specifications are subject to change without notice.